

TDPL97240

Radiation Tolerant UltraCMOS® Integer-N Frequency Synthesizer in an Epoxy-sealed, Ceramic, Non-hermetic Packaging for Low Phase Noise LEO Applications

Features

- Frequency range
 - 5 GHz in 10/11 prescaler modulus
 - 4 GHz in 5/6 prescaler modulus
- Phase noise floor figure of merit: -230 dBc/Hz
- Low power: 75 mA @ 2.8V
- Serial or direct mode access
- Packaged in an epoxy-coated, non-hermetic 48-lead, 7 x 7 mm CQFN
- 100 krad (Si) total dose - Typical

Product Description

Peregrine's TDPL97240 is a radiation tolerant high-performance, Integer-N PLL capable of frequency synthesis up to 5 GHz. The device is designed for commercial space applications and optimized for superior phase noise performance.

The TDPL97240 features a selectable prescaler modulus of 5/6 or 10/11, counters and a phase comparator as shown in *Figure 1*. Counter values are programmable through either a serial interface or directly hard-wired.

The TDPL97240 is available in a ceramic 7 x 7 mm, 48-lead CQFN and is manufactured on the UltraCMOS® process, a patented variation of silicon-on-insulator (SOI) technology on a sapphire substrate, offering excellent RF performance and intrinsic radiation tolerance.

Figure 1. Functional Diagram

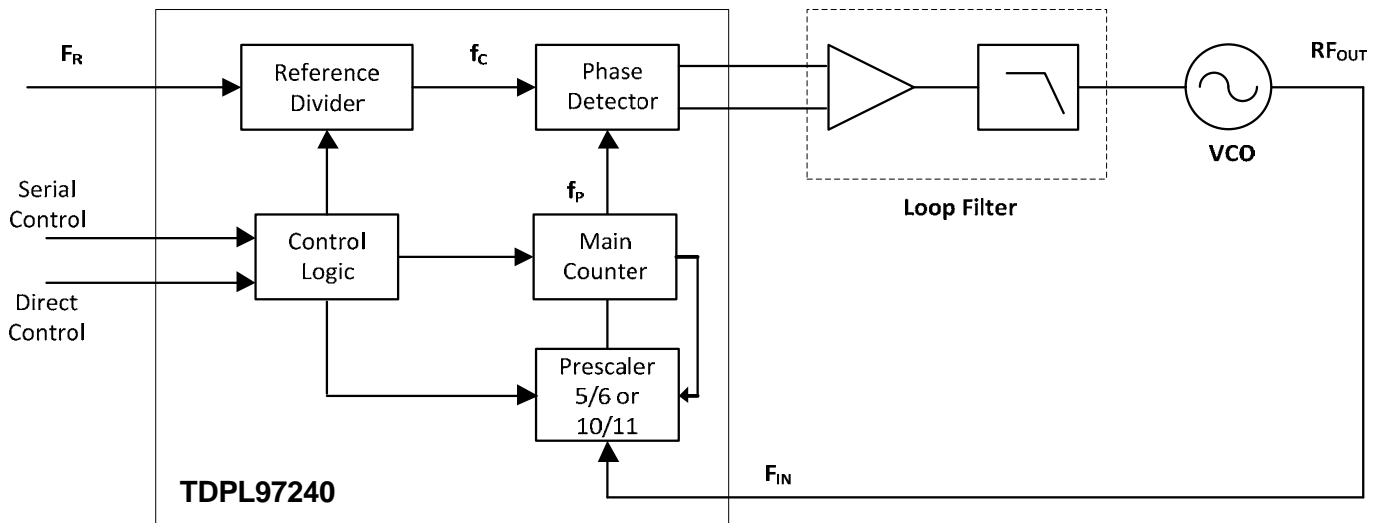


Figure 2. Pin Configurations (Top View)

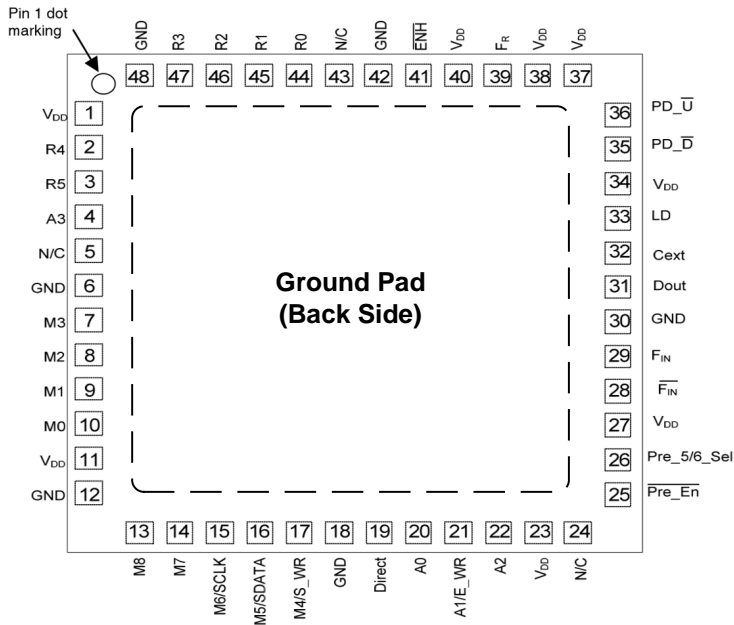


Table 1. Pin Descriptions

Pin #	Pin Name	Interface Mode	Type	Description
1	VDD	Both	Note 1	Power supply input. Input may range from 2.65V to 2.95V. Bypassing Recommended
2	R4	Direct	Input	R counter bit 4
3	R5	Direct	Input	R counter bit 5
4	A3	Direct	Input	A counter bit 3
5	N/C	Both	Note 3	No connect
6	GND	Direct		Ground
7	M3	Direct	Input	M counter bit 3
8	M2	Direct	Input	M counter bit 2
9	M1	Direct	Input	M counter bit 1
10	M0	Direct	Input	M counter bit 0
11	VDD	Both	Note 1	Power supply input. Input may range from 2.65V to 2.95V. Bypassing recommended
12	GND	Both		Ground
13	M8	Direct	Input	M counter bit 8
14	M7	Direct	Input	M counter bit 7
15	SCLK	Serial	Input	Serial clock input. SDATA is clocked serially into the 20-bit primary register (E_WR "low") or the 8-bit enhancement register (E_WR "high") on the rising edge of SCLK
	M6	Direct	Input	M counter bit 6

Table 1. Pin Descriptions (continued)

Pin #	Pin Name	Interface Mode	Type	Description
16	SDATA	Serial	Input	Binary serial data input. Input data entered MSB first
	M5	Direct	Input	M counter bit 5
17	S_WR	Serial	Input	Serial load enable input. While S_WR is "low", SDATA can be serially clocked. Primary register data is transferred to the secondary register on S_WR rising edge
	M4	Direct	Input	M counter bit 4
18	GND	Both		Ground
19	Direct	Direct	Input	Select "high" enables Direct Mode. Select "low" enables Serial Mode
20	A0	Direct	Input	A counter bit 0
21	E_WR	Serial	Input	Enhancement register write enable. While E_WR is "high", SDATA can be serially clocked into the enhancement register on the rising edge of SCLK
	A1	Direct	Input	A counter bit 1
22	A2	Direct	Input	A counter bit 2
23	V _{DD}	Both	Note 1	Power supply input. Input may range from 2.65V to 2.95V. Bypassing recommended
24	N/C	Both	Note 3	No connect
25	Pre_En	Direct	Input	Prescaler enable, active "low". When "high", F _{IN} bypasses the prescaler
26	Pre_5/6_Sel	Direct	Input	5/6 modulus select, active "high." When "low," 10/11 modulus selected
27	V _{DD}	Both	Note 1	Power supply input. Input may range from 2.65V to 2.95V. Bypassing recommended
28	— F _{IN}	Both	Input	Prescaler complementary input. A 22 pF bypass capacitor should be placed as close as possible to this pin and be connected in series with a 50Ω resistor to ground
29	F _{IN}	Both	Input	Prescaler input from the VCO, 5 GHz max frequency. A 22 pF coupling capacitor should be placed as close as possible to this pin and be connected in shunt to a 50Ω resistor to ground
30	GND	Both		Ground
31	Dout	Serial	Output	Data Out. The MSEL signal and the raw prescaler output are available on Dout through enhancement register programming
32	Cext	Both	Output	Logical "NAND" of PD_D and PD_U terminated through an on chip 2 kΩ series resistor. Connecting Cext to an external capacitor will low pass filter the input to the inverting amplifier used for driving LD
33	LD	Both	Output	Lock detect and open drain logical inversion of Cext. When the loop is in lock, LD is high impedance, otherwise LD is a logic low ("0")
34	V _{DD}	Both	Note 1	Power supply input. Input may range from 2.65V to 2.95V. Bypassing recommended
35	PD_D	Both	Output	PD_D is pulse down when f _p leads f _c
36	PD_U	Both	Output	PD_U is pulse down when f _c leads f _p
37	V _{DD}	Both	Note 1	Power supply input. Input may range from 2.65V to 2.95V. Bypassing recommended
38	V _{DD}	Both	Note 1	Power supply input. Input may range from 2.65V to 2.95V. Bypassing recommended

Table 1. Pin Descriptions (continued)

Pin #	Pin Name	Interface Mode	Type	Description
39	F _R	Both	Input	Reference frequency input
40	VDD	Both	Note 1	Power supply input. Input may range from 2.65V to 2.95V. Bypassing recommended
41	ENH	Serial	Input	Enhancement mode. When asserted low ("0"), enhancement register bits are functional
42	GND	Both		Ground
43	N/C	Both	Note 3	No connect
44	R0	Direct	Input	R counter bit 0
45	R1	Direct	Input	R counter bit 1
46	R2	Direct	Input	R counter bit 2
47	R3	Direct	Input	R counter bit 3
48	GND	Both		Ground
PAD	GND	Both		Back side ground pad must be soldered to PCB ground.

- Notes: 1. VDD pins 1, 11, 23, 27, 34, 37, 38 and 40 are connected by diodes and must be supplied with the same positive voltage level
 2. All digital input pins have 70 kΩ pull-down resistors to ground
 3. No connect pins can be left open or floating

Table 2. Operating Ratings

Parameter/Condition	Symbol	Min	Typ	Max	Unit
Supply voltage	V_{DD}	2.65	2.8	2.95	V
RF input power, CW 50 MHz–5 GHz	P_{MAX_CW}			10	dBm
Operating ambient temperature range	T_A	–40	+25	+85	°C

Table 3. Absolute Maximum Ratings

Parameter/Condition	Symbol	Min	Max	Unit
Supply voltage	V_{DD}	–0.3	3.3	V
Voltage on any input	V_I	–0.3	$V_{DD} + 0.3$	V
DC into any input	I_I	–10	+10	mA
DC into any output	I_O	–10	+10	mA
Thermal resistance	T_{JC}		33.4	°C/W
Junction temperature maximum	T_J		+125	°C
Storage temperature range	T_{ST}	–65	+150	°C
ESD voltage HBM ¹ All pins except pin 31	V_{ESD_HBM}		1000	V
ESD voltage HBM ^{1,2} On pin 31			300	V

Notes: 1. Human Body Model (MIL-STD-883 Method 3015).
 2. Pin 31 is not used in normal operation.

Exceeding absolute maximum ratings may cause permanent damage. Operation should be restricted to the limits in the Operating Ranges table. Operation between operating range maximum and absolute maximum for extended periods may reduce reliability.

Electrostatic Discharge (ESD) Precautions

When handling this UltraCMOS device, observe the same precautions that you would use with other ESD-sensitive devices. Although this device contains circuitry to protect it from damage due to ESD, precautions should be taken to avoid exceeding the rating specified.

Latch-Up Immunity

Unlike conventional CMOS devices, UltraCMOS devices are immune to latch-up.

ELDRS

UltraCMOS devices do not include bipolar minority carrier elements, and therefore do not exhibit enhanced low dose rate sensitivity.

Table 4. Single Event Effects¹

SEE Mode	Effective Linear Energy Transfer (LET) ²
SEL	86 MeV•cm ² /mg
SEFI	86 MeV•cm ² /mg
SEU	86 MeV•cm ² /mg
SET	30 MeV•cm ² /mg ³

Notes: 1. Testing performed using serial programming mode.
 2. SEE testing was conducted with Au, Ho, Xe, Kr, Cu ion species at 0° incidence.
 3. Minor transients (phase errors) observed resulting in self-recovering operation without intervention.

Table 5. DC Characteristics @ $V_{DD} = 2.65 - 2.95 \text{ V}$, $-40 \text{ }^\circ\text{C} \leq T_A \leq +85 \text{ }^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Condition	Min	Typ	Max	Unit
I_{DD}	Operational supply current	Prescaler disabled, $f_C = 50 \text{ MHz}$, $F_{IN} = 500 \text{ MHz}$		40	50	mA
		5/6 prescaler, $f_C = 50 \text{ MHz}$, $F_{IN} = 3 \text{ GHz}$		75	100	mA
		10/11 prescaler, $f_C = 50 \text{ MHz}$, $F_{IN} = 3 \text{ GHz}$		76	100	mA
Digital Inputs: All except F_R, F_{IN}, $\overline{F_{IN}}$						
V_{IH}	High level input voltage		$0.7 \times V_{DD}$			V
V_{IL}	Low level input voltage				$0.3 \times V_{DD}$	V
I_{IH}	High level input current	$V_{IH} = V_{DD} = 2.95\text{V}$			70	μA
I_{IL}	Low level input current	$V_{IL} = 0$, $V_{DD} = 2.95\text{V}$	-10			μA
Reference Divider input: F_R						
I_{IHR}	High level input current	$V_{IH} = V_{DD} = 2.95\text{V}$			300	μA
I_{ILR}	Low level input current	$V_{IL} = 0$, $V_{DD} = 2.95\text{V}$	-300			μA
Counter and phase detector outputs: PD_D, PD_U						
V_{OLD}	Output voltage LOW	$I_{out} = 6 \text{ mA}$			0.4	V
V_{OHD}	Output voltage HIGH	$I_{out} = -3 \text{ mA}$	$V_{DD} - 0.4$			V
Digital test outputs: D_{OUT} (totem-pole)						
V_{OLD}	Output voltage LOW	$I_{OUT} = 200 \mu\text{A}$			0.4	V
V_{OHD}	Output voltage HIGH	$I_{OUT} = -200 \mu\text{A}$	$V_{DD} - 0.4$			V
Lock detect outputs: (C_{EXT} <totem-pole>, LD <open-drain CMOS>)						
V_{OLC}	Output voltage LOW, C_{EXT}	$I_{out} = 100 \mu\text{A}$			0.4	V
V_{OHC}	Output voltage HIGH, C_{EXT}	$I_{out} = -100 \mu\text{A}$	$V_{DD} - 0.4$			V
V_{OLLD}	Output voltage LOW, LD	$I_{out} = 1 \text{ mA}$			0.4	V

Table 6. AC Characteristics @ $V_{DD} = 2.65 - 2.95 \text{ V}$, $-40 \text{ }^\circ\text{C} \leq T_A \leq +85 \text{ }^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Control interface and latches (see Figures 16 and 17)¹						
f_{Clk}	Serial data clock frequency ¹				10	MHz
t_{ClkH}	Serial clock HIGH time		30			ns
t_{ClkL}	Serial clock LOW time		30			ns
t_{DSU}	SDATA set-up time after SCLK rising edge		10			ns
t_{DHLd}	SDATA hold time after SCLK rising edge		10			ns
t_{PW}	S_WR pulse width		30			ns
t_{CWR}	SCLK rising edge to S_WR rising edge		30			ns
t_{CE}	SCLK falling edge to E_WR transition		30			ns
t_{WRC}	S_WR falling edge to SCLK rising edge		30			ns
t_{EC}	E_WR transition to SCLK rising edge		30			ns
Main divider 5/6 (including prescaler)						
F_{IN}	Operating frequency		800		4000	MHz
$P_{\text{F_IN}}$	Input level range	External AC coupling 800 MHz–4 GHz	-5^2		7	dBm
Main divider 10/11 (including prescaler)						
F_{IN}	Operating frequency		800		5000	MHz
$P_{\text{F_IN}}$	Input level range	External AC coupling 800 MHz–<4 GHz 4–5 GHz	-5^2 2		7 7	dBm dBm
Main divider (prescaler bypassed)						
F_{IN}	Operating frequency		50		800	MHz
$P_{\text{F_IN}}$	Input level range	External AC coupling	-5^2		7	dBm
Reference divider						
F_{R}	Operating frequency				100	MHz
$P_{\text{F_R}}$	Reference input power ³	Single-ended input	-1^4		7	dBm
Phase detector						
f_{c}	Comparison frequency				100	MHz

Table 6. AC Characteristics @ V_{DD} = 2.65 – 2.95 V, -40 °C ≤ T_A ≤ +85 °C, unless otherwise specified (continued)

Symbol	Parameter	Condition	Min	Typical	Max	Unit
SSB phase noise 5/6 prescaler (F_{IN} = 3 GHz, P_{F,R} = +5 dBm, f_c = 50 MHz, LBW = 500 kHz)						
Φ _N	Phase noise	100 Hz offset		-100	-93	dBc/Hz
Φ _N	Phase noise	1 kHz offset		-109	-101	dBc/Hz
Φ _N	Phase noise	10 kHz offset		-116	-110	dBc/Hz
Φ _N	Phase noise	100 kHz offset		-118	-114	dBc/Hz
SSB phase noise 10/11 prescaler (F_{IN} = 3 GHz, P_{F,R} = +5 dBm, f_c = 50 MHz, LBW = 500 kHz)						
Φ _N	Phase noise	100 Hz offset		-98	-91	dBc/Hz
Φ _N	Phase noise	1 kHz offset		-104	-98	dBc/Hz
Φ _N	Phase noise	10 kHz offset		-111	-107	dBc/Hz
Φ _N	Phase noise	100 kHz offset		-117	-113	dBc/Hz
Phase noise figure of merit (FOM)⁵						
FOM _{flicker}	Flicker figure of merit	5/6 prescaler		-268	-265	dBc/Hz
		10/11 prescaler		-263	-259	dBc/Hz
FOM _{floor}	Floor figure of merit	5/6 prescaler		-230	-227	dBc/Hz
		10/11 prescaler		-229	-225	dBc/Hz
FOM _{flicker}	PN _{flicker} = FOM _{flicker} + 20log (F _{IN}) – 10log (f _{offset})					dBc/Hz
FOM _{floor}	PN _{floor} = FOM _{floor} + 10log (f _c) + 20log (F _{IN} /f _c)					dBc/Hz
FOM _{total}	PN _{total} = 10log (10 [PN _{flicker} /10] + 10 [PN _{floor} /10])					dBc/Hz

- Notes: 1. Timing parameters are guaranteed through design characterization and not tested in production.
 f_{clk} is verified during the functional pattern test. Serial programming sections of the functional pattern are clocked at 10 MHz to verify f_{clk} specification.
2. 0 dBm minimum is recommended for improved phase noise performance when sine-wave is applied.
3. CMOS logic levels can be used to drive the reference input. If the V_{DD} of the CMOS driver matches the V_{DD} of the PLL IC, then the reference input can be DC coupled. Otherwise, the reference input should be AC coupled. For sine-wave inputs, the minimum amplitude needs to be 0.5 V_{PP}. The maximum level should be limited to prevent ESD diodes at the pin input from turning on. Diodes will turn on at one forward-bias diode drop above V_{DD} or below GND. The DC voltage at the Reference input is V_{DD}/2.
4. +2 dBm or higher is recommended for improved phase noise performance.
5. The phase noise can be separated into two normalized specifications: a floor figure of merit and a flicker figure of merit. To accurately measure the phase noise floor without the contribution of the flicker noise, the loop bandwidth is set to 500 kHz and the phase noise is measured at a frequency offset near 100 kHz. The flicker noise is measured at a frequency offset ≤ 1000 Hz. The formula assumes a -10 dB/decade slope versus frequency offset.

Figure 4. Equivalent Input Diagram: Digital Input

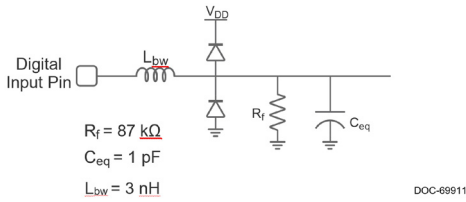


Figure 5. Equivalent Input Diagram: Reference Input

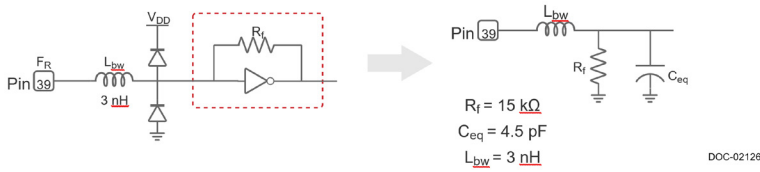


Figure 6. Equivalent Input Diagram: Main Input

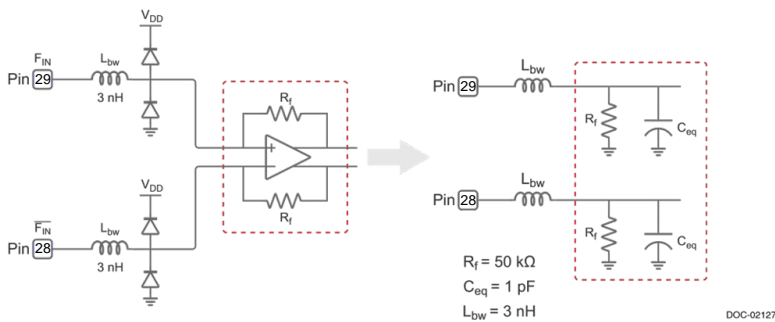
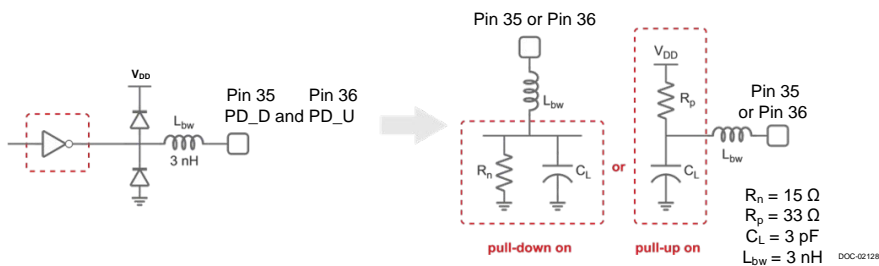


Figure 7. Equivalent Output Diagram

PD_D (Pin 35) and PD_U (Pin 36) Output



Typical Performance Data @ 25 °C, $V_{DD} = 2.8\text{ V}$, $f_c = 50\text{ MHz}$ and $F_{IN} = 3\text{ GHz}$, unless otherwise noted

Figure 8. Typical Phase Noise (5/6 Prescaler)

$F_{IN} = 3\text{ GHz}$, $V_{DD} = 2.8\text{ V}$, Loop Bandwidth = 500 kHz

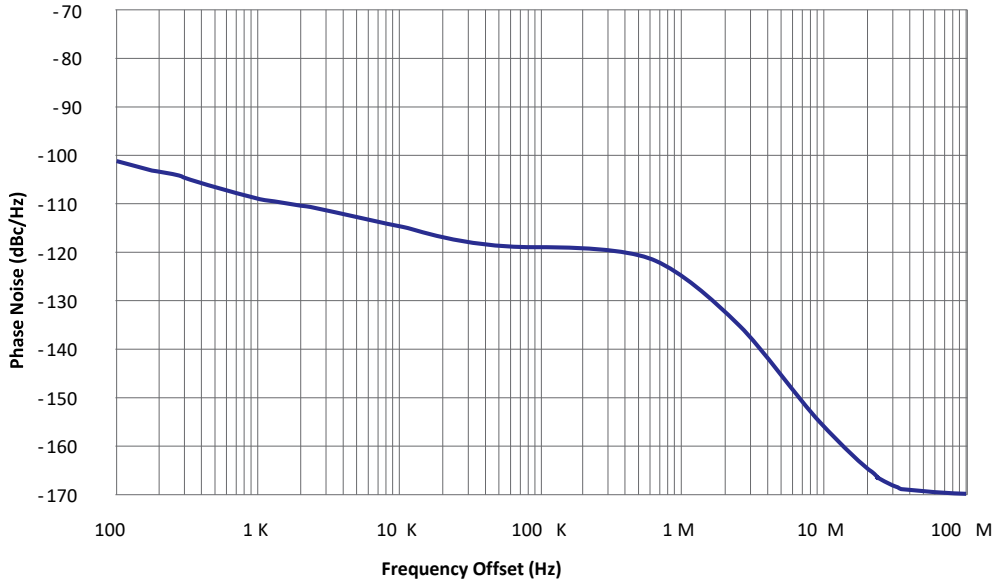
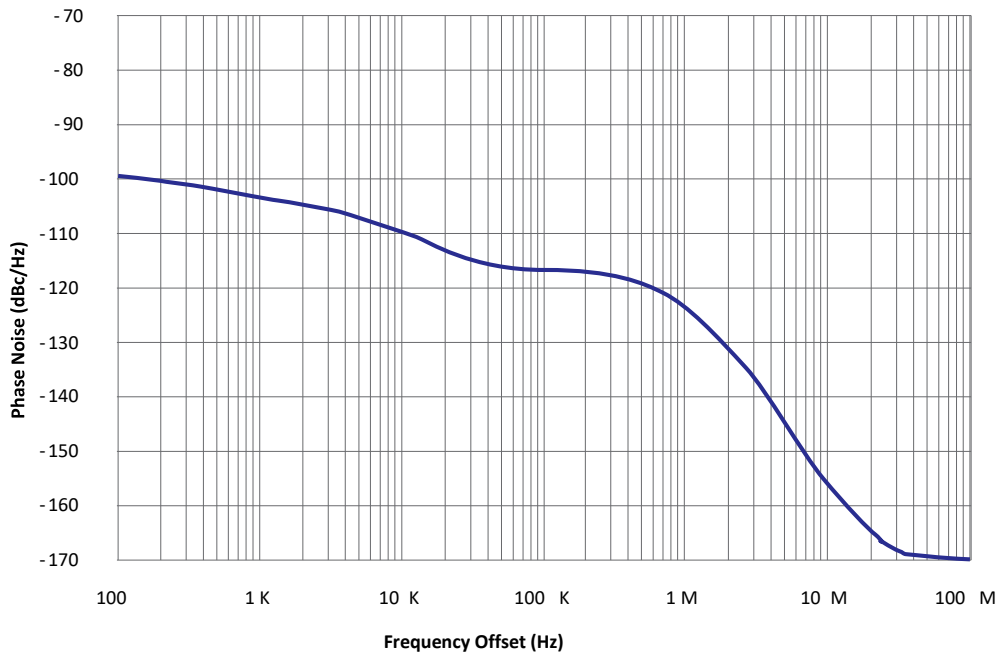


Figure 9. Typical Phase Noise (10/11 Prescaler)

$F_{IN} = 3\text{ GHz}$, $V_{DD} = 2.8\text{ V}$, Loop Bandwidth = 500 kHz



Typical Performance Data @ 25 °C, V_{DD} = 2.8 V, f_C = 50 MHz and F_{IN} = 3 GHz

Figure 10. FOM vs. Reference Power and Temp (5/6 Prescaler)

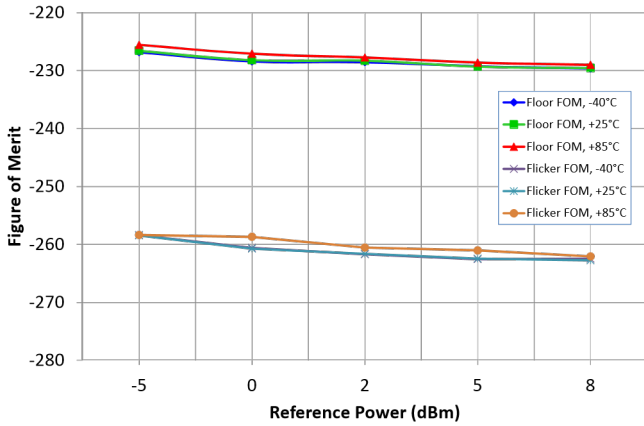


Figure 11. FOM vs. Reference Power and Temp (10/11 Prescaler)

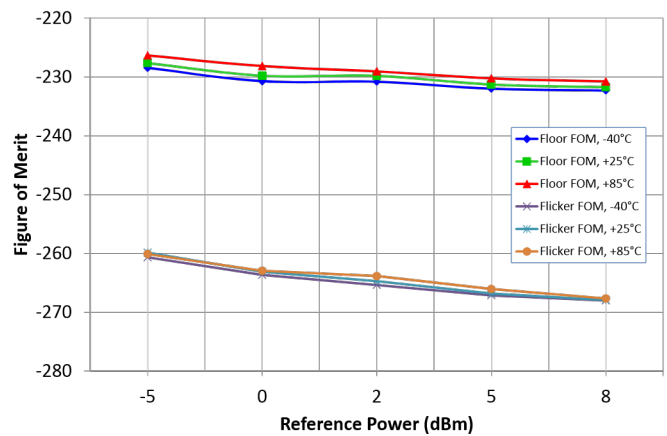


Figure 12. FOM vs. Temp and Supply Voltage (5/6 Prescaler, P_{FIN} = 2 dBm)

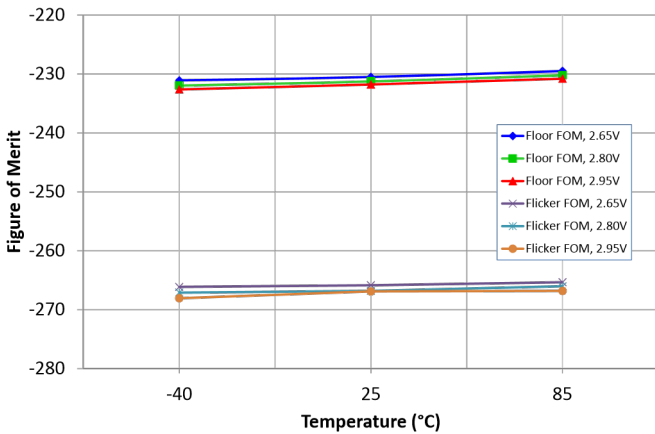


Figure 13. FOM vs. Temp and Supply Voltage (10/11 Prescaler, P_{FIN} = 2 dBm)

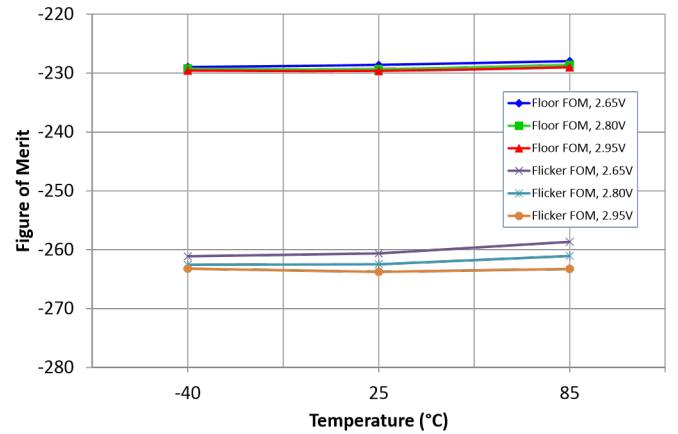


Figure 10. RF Sensitivity vs. F_{IN} and Temp (5/6 Prescaler, V_{DD} = 2.65V)*

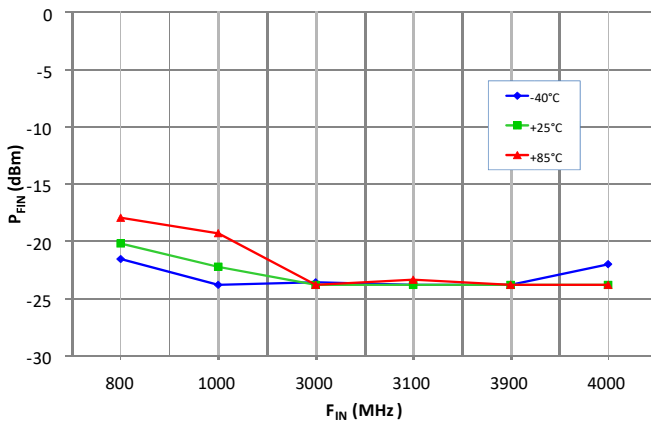
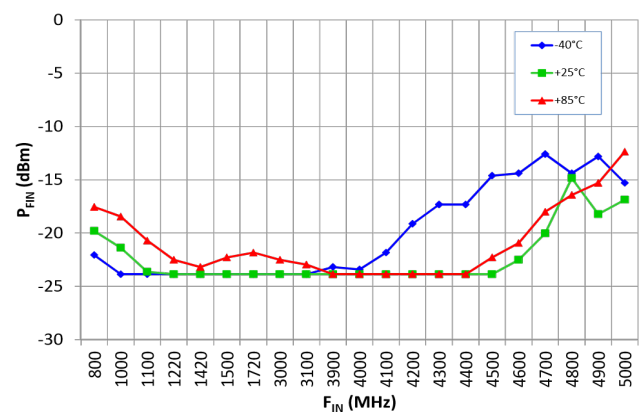


Figure 11. RF Sensitivity vs. F_{IN} and Temp (10/11 Prescaler, V_{DD} = 2.65V)*



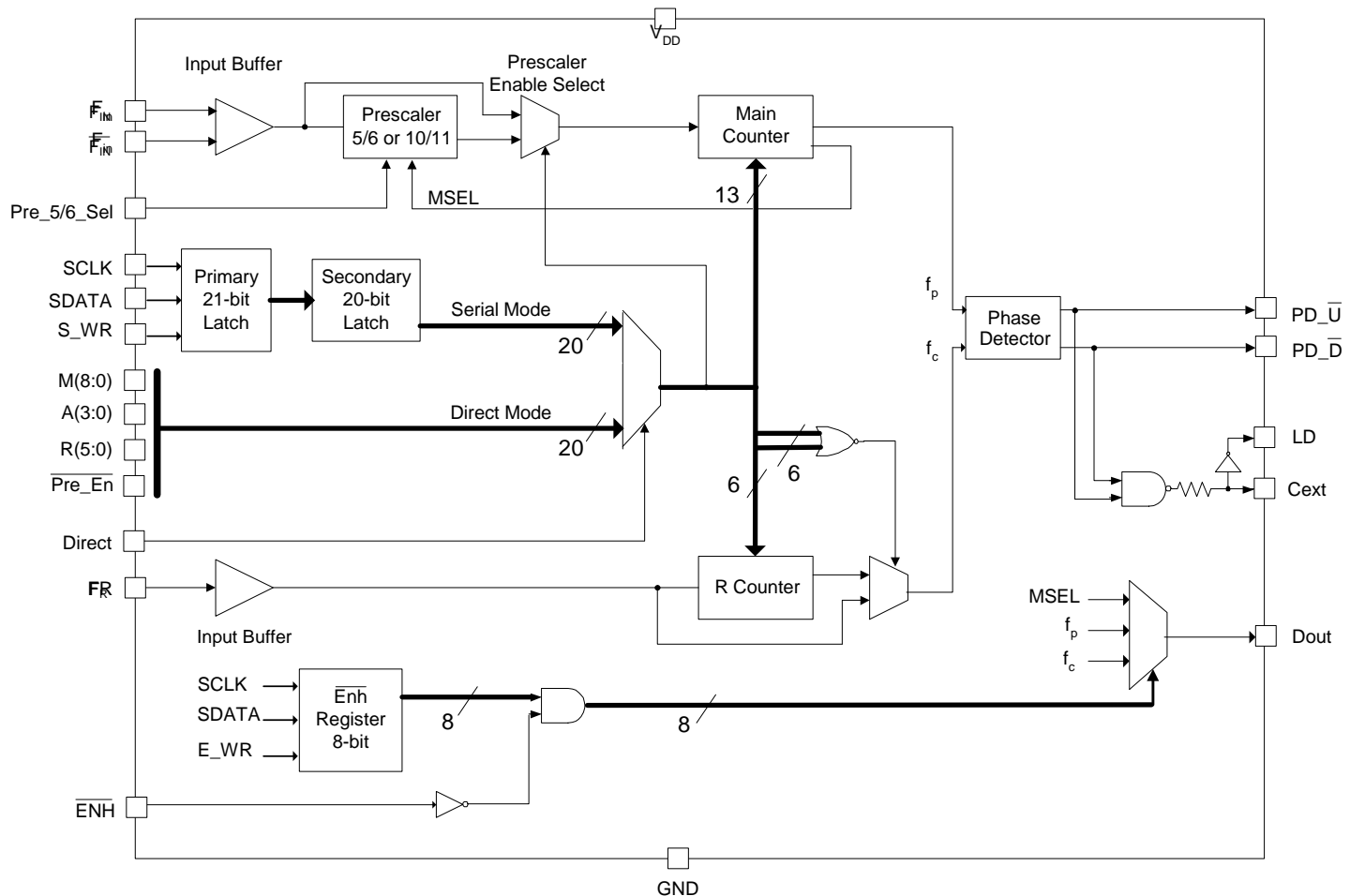
Note: * RF sensitivity is the minimum input power level required for the PLL to maintain lock. Operating at these levels does not guarantee the SSB phase noise performance in Table 6.

Functional Description

The TDPL97240 consists of a prescaler, counters, a phase detector, and control logic. The dual modulus prescaler divides the VCO frequency by either 5/6 or 10/11, depending on the value of the modulus select. Counters “R” and “M” divide the reference and prescaler output, respectively, by integer values stored in a 21-bit register. An additional counter (“A”) is used in the modulus

select logic. The phase-frequency detector generates up and down frequency control signals. The control logic includes a selectable chip interface. Data can be written via serial bus or hardwired directly to the pins. There are also various operational and test modes and a lock detect output.

Figure 16. Functional Block Diagram



Main Counter Chain

Normal Operating Mode

The main counter chain divides the RF input frequency, F_{IN} , by an integer derived from the user-defined values in the “M” and “A” counters. It is composed of the 5/6 or 10/11 selectable modulus prescaler, modulus select logic, and 9-bit M counter. The prescaler can be set to either 5/6 or 10/11 based on the Pre_5/6_SEL pin. Setting Pre_en “low” enables the 5/6 or 10/11 prescaler. Setting Pre_en “high” allows F_{IN} to bypass the prescaler and powers down the prescaler.

The output from the main counter chain, f_p , is related to the VCO frequency, F_{in} , by the following equation:

$$f_p = F_{IN} / [10 \times (M + 1) + A] \quad (1)$$

where $A \leq M + 1$, $1 \leq M \leq 511$

Or

$$f_p = F_{IN} / [5 \times (M + 1) + A]$$

where $A \leq M + 1$, $1 \leq M \leq 511$

When the loop is locked, F_{IN} is related to the reference frequency, F_R , by the following equation:

$$F_{IN} = [10 \times (M + 1) + A] \times [F_R / (R + 1)] \quad (2)$$

where $A \leq M + 1$, $1 \leq M \leq 511$

Or

$$F_{IN} = [5 \times (M + 1) + A] \times [F_R / (R + 1)]$$

where $A \leq M + 1$, $1 \leq M \leq 511$

A consequence of the upper limit on A is that in Integer-N mode, to obtain contiguous channels,

F_{IN} must be = $90 \times [F_R / (R + 1)]$ with 10/11 modulus

F_{IN} must be = $20 \times [F_R / (R + 1)]$ with 5/6 modulus

The A counter can accept values as high as 15, but in typical operation it will cycle from 0 to 9 between increments in M. Programming the M counter with the minimum allowed value of “1” will result in a minimum M counter divide ratio of “2”.

Prescaler Bypass Mode

Setting Pre_en “high” allows F_{IN} to bypass and power down the prescaler. In this mode, the 5/6 or 10/11 prescaler and A register are not active, and the input VCO frequency is divided by the M counter directly. The following equation relates F_{in} to the reference frequency, F_R :

$$F_{IN} = (M + 1) \times [F_R / (R + 1)] \quad (3)$$

where $1 \leq M \leq 511$

Reference Counter

The reference counter chain divides the reference frequency, F_R , down to the phase detector comparison frequency, f_c .

The output frequency of the 6-bit R counter is related to the reference frequency by the following equation:

$$f_c = F_R / (R + 1) \quad (4)$$

where $0 \leq R \leq 63$

Note that programming R with “0” will pass the reference frequency, F_R , directly to the phase detector.

Serial Interface Mode

While the E_WR input is “low” and the S_WR input is “low”, serial input data (SDATA input), B₀ to B₂₀, is clocked serially into the primary register on the rising edge of SCLK, MSB (B₀) first. The contents from the primary register are transferred into the secondary register on the rising edge of S_WR according to the timing diagram shown in *Figure 17*. Data is transferred to the counters as shown in *Table 7*.

While the E_WR input is “high” and the S_WR input is “low”, serial input data (SDATA input), B₀ to B₇, is clocked serially into the enhancement register on the rising edge of SCLK, MSB (B₀) first. The enhancement register is double buffered

to prevent inadvertent control changes during serial loading, with buffer capture of the serially-entered data performed on the falling edge of E_WR according to the timing diagram shown in *Figure 17*. After the falling edge of E_WR, the data provides control bits as shown in *Tables 8 and 9* with bit functionality enabled by asserting the ENH input “low”.

Direct Interface Mode

Direct Interface Mode is selected by setting the Direct input “high”.

Counter control bits are set directly at the pins as shown in *Table 7*.

Table 7. Primary Register Programming

Interface Mode	ENH	R ₅	R ₄	M ₈	M ₇	Pre_en	M ₆	M ₅	M ₄	M ₃	M ₂	M ₁	M ₀	R ₃	R ₂	R ₁	R ₀	A ₃	A ₂	A ₁	A ₀	ADDR
Serial*	1	B ₀	B ₁	B ₂	B ₃	B ₄	B ₅	B ₆	B ₇	B ₈	B ₉	B ₁₀	B ₁₁	B ₁₂	B ₁₃	B ₁₄	B ₁₅	B ₁₆	B ₁₇	B ₁₈	B ₁₉	B ₂₀
Direct	1	R ₅	R ₄	M ₈	M ₇	Pre_en	M ₆	M ₅	M ₄	M ₃	M ₂	M ₁	M ₀	R ₃	R ₂	R ₁	R ₀	A ₃	A ₂	A ₁	A ₀	0

Note: * Serial data clocked serially on SCLK rising edge while E_WR “low” and captured in secondary register on S_WR rising edge.

↑
MSB (first in)

↑
(last in) LSB

Table 8. Enhancement Register Programming

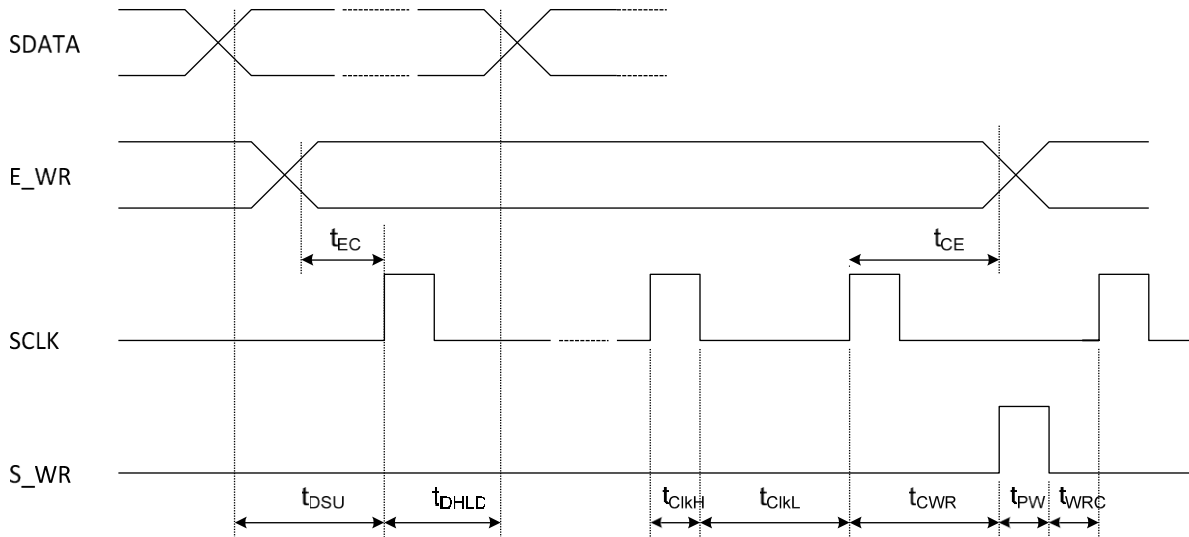
Interface Mode	ENH	Direct	Reserved	Reserved	f _p output	Power Down	Counter load	MSEL output	f _c output	LD Disable
Serial*	0	0	B ₀	B ₁	B ₂	B ₃	B ₄	B ₅	B ₆	B ₇

Note: * Serial data clocked serially on SCLK rising edge while E_WR “high” and captured in the double buffer on E_WR falling edge.

↑
MSB (first in)

↑
(last in) LSB

Figure 17. Serial Interface Mode Timing Diagram



Enhancement Register

The functions of the enhancement register bits are shown below with all bits active “high”.

Table 9. Enhancement Register Bit Functionality

Bit Function		Description
Bit 0	Reserve*	Reserved.
Bit 1	Reserve*	Reserved.
Bit 2	f_p output	Drives the M counter output onto the D _{OUT} output.
Bit 3	Power down	Power down of all functions except programming interface.
Bit 4	Counter load	Immediate and continuous load of counter programming.
Bit 5	MSEL output	Drives the internal dual modulus prescaler modulus select (MSEL) onto the D _{OUT} output.
Bit 6	f_c output	Drives the reference counter output onto the D _{OUT} output.
Bit 7	LD Disable	Disables the LD pin for quieter operation.

Note: * Program to 0.

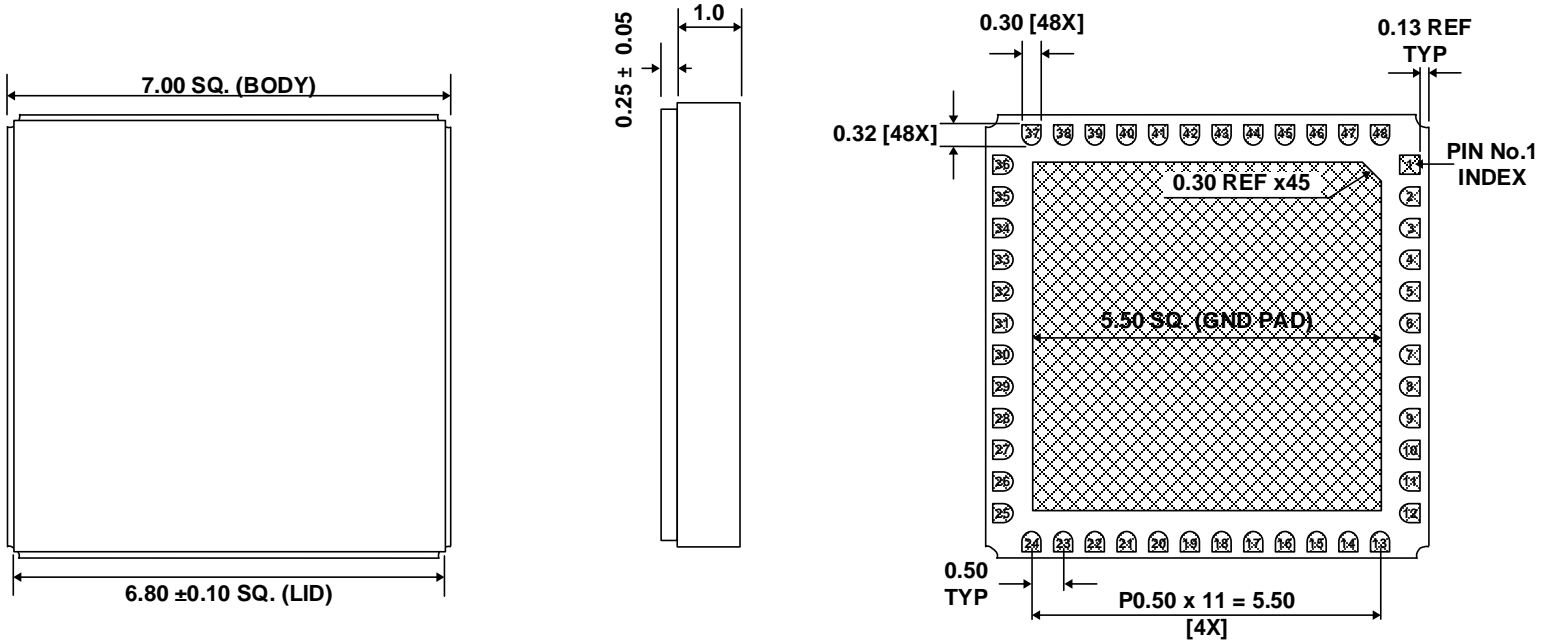
Phase Detector

The phase detector is triggered by rising edges from the main Counter (f_p) and the reference counter (f_c). It has two outputs, namely PD_U, and PD_D. If the divided VCO leads the divided reference in phase or frequency (f_p leads f_c), PD_D pulses “low”. If the divided reference leads the divided VCO in phase or frequency (f_r leads f_p), PD_U pulses “low”. The width of either pulse is directly proportional to phase offset between the two input signals, f_p and f_c . The phase detector gain is 400 mV/radian.

PD_U and PD_D are designed to drive an active loop filter which controls the VCO tune voltage. PD_U pulses result in an increase in VCO frequency and PD_D results in a decrease in VCO frequency.

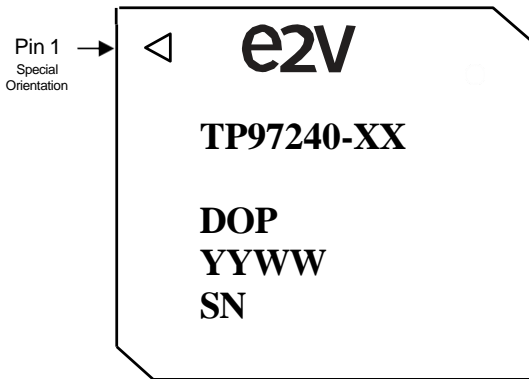
A lock detect output, LD is also provided, via the pin C_{EXT}. C_{EXT} is the logical “NAND” of PD_U and PD_D waveforms, which is driven through a series 2 k Ω resistor. Connecting C_{EXT} to an external shunt capacitor provides integration. C_{EXT} also drives the input of an internal inverting comparator with an open drain output. Thus LD is an “AND” function of PD_U and PD_D. See *Figure 16* for a functional block diagram of this circuit.

Figure 21. Package Drawing (dimensions are in millimeters)
 48-lead CQFN



ALL DIMS IN MM.
TOLERANCE = x.xx +/- 0.15 UNLESS OTHERWISE NOTED.
NOT TO SCALE.

Figure 22. Top Marking Specifications



Not to scale


Line 1: Pin 1 indicator \triangle , e2v logo (may be )
 Line 2: Part number / XX will be specified by the purchase order as -77 or -88...see Ordering Information below for more detail
 Line 3: DOP# / This is an e2v internal code / 5 digits
 Line 4: Date code / This is the last two digits of the year plus the 2-digit code of the work week
 Line 5: SN / IC's Serial Number

Table 10. Ordering Information

Order Code	Description	Package	Shipping Method
TDPL97240-77	25C Tested EM Units	48-lead QFN	40 units/tray
TDPL97240-88	Qualified to EEE-INST-002 Level 3	48-lead QFN	40 units/tray

Table 11. Document Revision History

Document Number	Description	Updates	Revision / Date
TDPL97240-ProdSpec-050123-v0.1a	TDPL97240 Product Specification	Original Release	v0.1a on 05_01_2023

Sales Contact and Information

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Advance Information: The product is in a formative or design stage. The datasheet contains design target specifications for product development. Specifications and features may change in any manner without notice.

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Product Specification: The datasheet contains final data. In the event pSemi decides to change the specifications, pSemi will notify customers of the intended changes by issuing a CNF (Customer Notification Form).

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